In the claims:

A listing of the claims and their status is provided below:

Claims 1-2. Cancel

Claim 3 (currently amended). The head device as set forth in claim ~~1~~ 7, wherein the shifted amount of the adjacent pads in the second direction is larger than a dimension of the electrode pad in the second direction.

Claim 4. Cancel

Claim 5 (currently amended). The magnetoresistive head device as set forth in claim ~~1~~ 7, wherein two of the electrode pads are electrically connected to either one of the magnetoresistive elements or one of the coils.

Claim 6 (currently amended). The magnetoresistive head as set forth in claim ~~1~~ 7, wherein each of the coils is formed on a surface of the wafer substrate.

Claim 7 (original). A multi-channel magnetoresistive head device, comprising:

a wafer substrate,

a plurality of magnetoresistive heads arranged on the wafer substrate in a first direction, and each electrically connected to and associated magnetoresistive head, wherein respective adjacent electrode pads are shifted from each other in a second direction perpendicular to said first direction; and

a flexible printed board, on which a plurality of electrode pads are arranged in a third direction, wherein

each of the electrode pads on the flexible printed board is electrically connected to an associated electrode pad on the wafer substrate, and

respective adjacent electrode pads are shifted from each other in a fourth direction perpendicular to said third direction.

Claim 8 (original). The head device as in claim 7, wherein the third direction aligns with the first direction, and the fourth direction aligns with the second direction.

Claim 9 (original). The head device as in claim 7, wherein the pads arranged on the wafer substrate in the first direction are wired to respective pads on a flexible printed board, and the pads in the second direction are wired to respective pads on a flexible printed circuit board.